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General Information

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|--------------------------|---|
| Series | SMD Comm X7R FE |
| Style | SMD Chip |
| Description | SMD, MLCC, FE-CAP, Floating Electrode, Temperature Stable |
| Features | FE-CAP, Floating Electrode, Temperature Stable |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 11 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

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|----------------------|------------------|
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| T | 0.78mm +/-0.10mm |
| S | 0.7mm MIN |
| B | 0.5mm +/-0.25mm |
| Case Code (EIA / mm) | 0805 / 2012 |

Packaging Specifications

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|--------------------|------------------------|
| Packaging | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000 |

Specifications

| | |
|--|---|
| Capacitance | 0.033 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1 kHz 1.0Vrms |
| Dissipation Factor | 2.5% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 30.303 GOhms |

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